

MKP Film Capacitor

Material Data Sheet

Product Class	MKP Film Capacitors		
	Series B3264X Large		
Date	18/11/2019		
IMDS ID if available	NA		
Version	5.02.1a (03/2019)		



Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Light metal	1B	Al	100	7429-90-5	0.3	
	Heavy metal	1C	Sn	97	7440-31-5	0.00	
	Heavy metal	1C	Cu	3	7440-50-8	2.06	
	Heavy metal	1C	Zn	100	7440-66-6	3	
	Thermoplastic	2A	PET	100	25038-59-9	10.5	
	Thermoplastic	2A	PP	100	9003-07-0	14.5	
Encapsulation	Thermoplastic	2A	PBT	85 or70 or 55	26062-94-2	27 or 22 or 17	
	Flame retardant No	Not available	N,N Ethylenebis(Tetrabromophthalimide),	15	32588-76-4	4	
			Sb ₂ O ₃	13	1309-64-4	1	
	Inorganic, solid	4A	Glass Fiber	0 or 15 or 30	65997-17-3	0 or 5 or 10	
	Duromer	2D	Ероху	50	24969-06-0	18.5	
	Inorganic, solid	5A	Al (OH) ₃	45	21645-51-2	16	
	Plasticizer	Not available	Other*	5	Not available	1.5	
Termination	Heavy Metal	1C	Cu	93.7	7440-50-8	7.5	
	Heavy Metal	1C	Sn	6.3	7440-31-5	0.5	
(*1): Substitute t	he x bv number indi	cated in part numbers		•	Sum in total:	100	•

(1). Substitute the X by number indicated in part numbers						ouin in total.		00	
sizes [mm]	weight range [g]	part numbers(*1)	sizes [mm]	weight range [g]	part numbers(*1)	Size (mm)	weight range [g]	part numbers(*1)	_
13,0 x 4,0 x 9,0	0,7	x=1	18,0 x 9,0 x 17,5	4,5	x=2	26.5x11.0x20.5	9.0	x=3	

Not Part of a Product Class

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* " () ()					

*) others: .(not declarable or prohibited substances acc. GADSL)

Important remarks:

- The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated.
- This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH HEGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PUPPOSE.

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (☑ valid ☐ not valid)

☑ no exemptions;

□ Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;

☐ Exemption 6 (b): Lead as an alloying element in aluminum containing up to 0,4 % lead by weight;

 \square Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;

□ Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);

Exemption 7 (c)-1: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;

□ Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;

□ Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;

□ Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;

☐ Other Exemption than above

^{**)} typical mass percentage of substance

